Product Change Notification: DSNO-22WFHG168

Date:

26-Oct-2026

Product Category:

Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Power Management - System Supervisors/Voltage Detectors

Notification Subject:

CCB 8448 Initial Notice: Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.

Affected CPNs:

DSNO-22WFHG168_Affected_CPN_10262026.pdf
DSNO-22WFHG168_Affected_CPN_10262026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.

Pre and Post Summary Changes:

		Pre Change		Post Change		Change (Yes/No)
Assembly Site		Microchip Technology Thailand (Branch) (MMT)		Microchip Technology Thailand (Branch) (MMT)		No
Wire Material		CuPdAu		CuPdAu		No
Die Attach Material		84-3J (PFAS-free)	8006NS (PFAS-free)	84-3J (PFAS-free)	8006NS (PFAS-free)	No
Molding Compound Material		G600V		G600V	G630AY	Yes
Lead-Frame Material		CDA194		CDA194		No
Lead-Frame Paddle Size	**5L SOT-23 (1.6mm)**	66 x 48 mils		66 x 48 mils		No
	6L SOT-23 (1.6mm)	72 x 41 mils		72 x 41 mils		No
Lead-Frame DAP Surface Prep		Ag-RT		Ag		Yes
Lead-Frame Design		See 'Pre and Post Change Summary' attachment for comparison.				Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying G630AY as additional molding compound material at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: December 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					**>**	**December 2026**			
Work Week	40	41	42	43	44		49	50	51	52
Initial PCN Issue Date					x					
Qual Report Availability							x			
Final PCN Issue Date							x			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 26, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-22WFHG168_Qual_Plan.pdf
PCN_DSNO-22WFHG168_Pre and_Post_Change Summary.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

TC1270ANLAVCTTR

MCP6291RT-E/OT

MCP6L91RT-E/OT

MCP6271RT-E/OT

MCP6L71RT-E/OT

MCP6281RT-E/OT

TC1270ANRVCTTR

TC1270ANSVCTTR

TC1270ANTVCTTR

TC1270ANMVCTTR

TC1270ANLVCTTR

MCP6001T-I/OT

TC1270ANRAVCTTR

TC1270ANSAVCTTR

TC1270ANTAVCTTR

MCP6L1RT-E/OT

MCP6273T-E/CH

MCP6283T-E/CH

MCP6293T-E/CH

MCP6241RT-E/OT

MCP6541RT-I/OT

MCP6541RT-E/OT

MCP6546RT-I/OT

MCP6546RT-E/OT

MCP6001RT-I/OT

MCP6001RT-E/OT

MCP6L01RT-E/OT

MCP6401RT-E/OT

MCP111T-360E/OT

MCP111T-370E/OT

MCP6231RT-E/OT

TC1270ARAVCTTR

TC1270ASAVCTTR

TC1270ATAVCTTR

TC1270AMAVCTTR

TC1270ALAVCTTR

TC1271ARAVCTTR

TC1271ASAVCTTR

TC1271ATAVCTTR

TC1271AMAVCTTR

TC1271ALAVCTTR

MCP6043T-E/CH

MCP6541T-I/OT

MCP6541T-E/OT

MCP6546T-I/OT

MCP6546T-E/OT

MCP603T-I/CH

MCP603T-E/CH

MCP601RT-I/OT

MCP601RT-E/OT

TC1270ATBVCTTR

TC1270AMBVCTTR

TC1270ALBVCTTR

TC1271ARBVCTTR

TC1271ASBVCTTR

TC1270ANMAVCTTR

TC1271ATBVCTTR

TC1271AMBVCTTR

TC1271ALBVCTTR

TC1270ANRBVCTTR

TC1270ANSBVCTTR

TC1270ANTBVCTTR

TC1270ANMBVCTTR

TC1271ASVCTTR

TC1271ATVCTTR

TC1271AMVCTTR

TC1271ALVCTTR

MCP6001T-E/OT

TC1270ANLBVCTTR

TC1270ARVCTTR

TC1270ASVCTTR

TC1270ATVCTTR

TC1270AMVCTTR

TC1270ALVCTTR

TC1271ARVCTTR

MCP6L01T-E/OT

MCP6G01RT-E/OT

MCP6001T-I/OT-HCM

MCP6021RT-E/OT

MCP6271T-E/OT

MCP6281T-E/OT

MCP6291T-E/OT

MCP6L71T-E/OT

MCP6L91T-E/OT

MCP6143T-E/CH

MCP6043T-I/CH

TC1270ARBVCTTR

TC1270ASBVCTTR

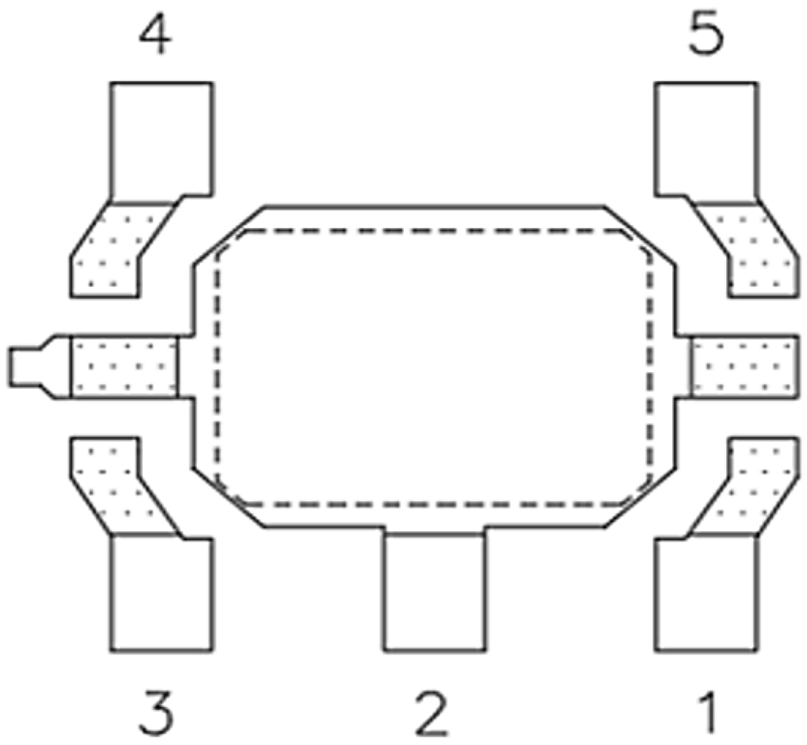
CCB 8448
Pre and Post Change Summary
PCN #: DSNO-22WFHG168



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Lead Frame Comparison – 5L SOT-23 (1.6mm)

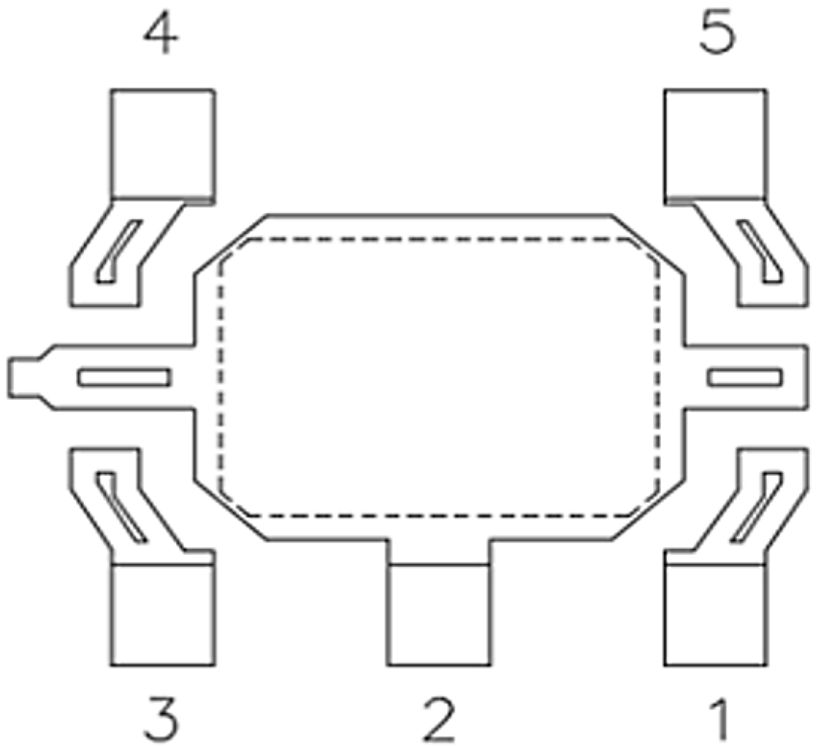
Pre Change



DAP Surface Prep	Ag-RT

Note: Not to scale

Post Change



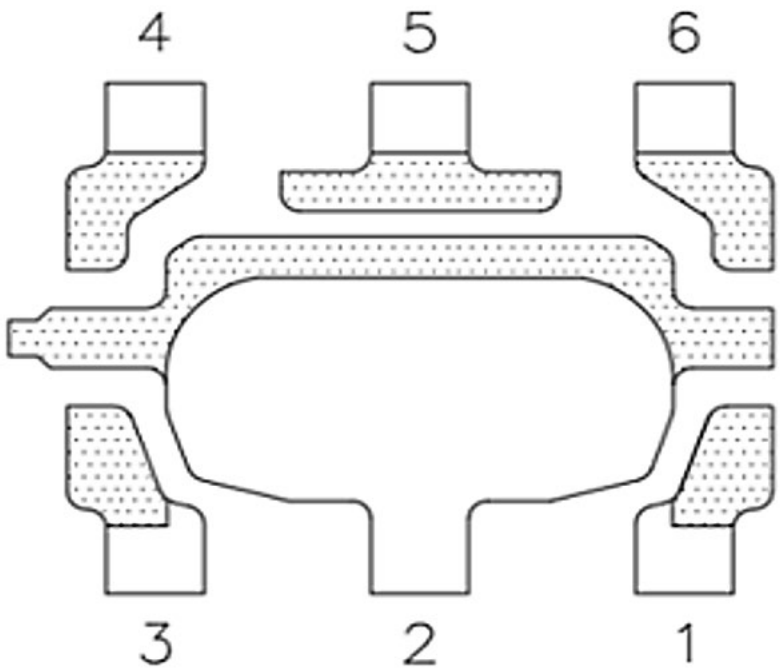
DAP Surface Prep	Ag

Note: Not to scale

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Lead Frame Comparison – 6L SOT-23 (1.6mm)

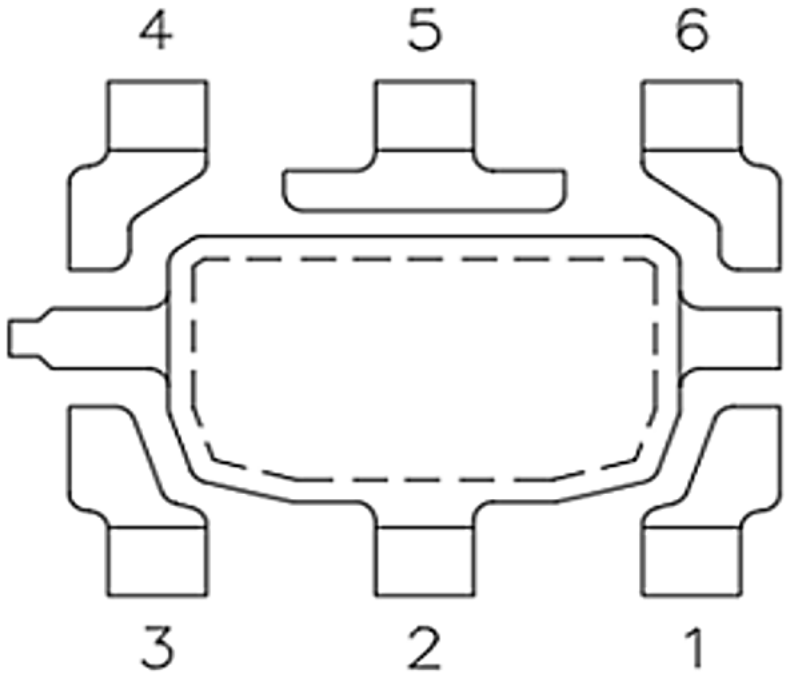
Pre Change



DAP Surface Prep	Ag-RT

Note: Not to scale

Post Change



DAP Surface Prep	Ag

Note: Not to scale

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QUALIFICATION PLAN SUMMARY

PCN #: DSNO-22WFHG168

Date:
October 7, 2026

Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.

Purpose: **Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.**

CCB No.: **8448**

Misc.	Assembly site		MMT
	BD Number		BD-004628-01
	MP Code (MPC)		A7BZ4YC8XF00
	Part Number (CPN)		MCP6293T-E/CH
	MSL information		MSL1
	Assembly Shipping Media (T/R, Tube/Tray)		T/R
	Base Quantity Multiple (BQM)		3000
	Reliability Site		MTAI
Lead-Frame	Paddle size		72 x 41 mils 66 x 48 mils
	Material		CDA194
	DAP Surface Prep		Ag
	Treatment		Non-Roughening
	Process		Stamped
	Lead-lock		No
	Part Number		10100602, 10100502
	Lead Plating		Matte tin
Bond Wire	Material		CuPdAu
Die Attach	Part Number		84-3J/8006NS
	Conductive		No
	Backside Coat (If Applicable)	Material:	8006NS
		Thickness:	25um
		Conductive:	No
MC	Part Number		G630AY
PKG	Package Type		SOT-23
	Pin/Ball Count		6

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5			30 bonds from a min. 5 devices.
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5			
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5			
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25C and hot temp 125C. Note: Prefer to use 150°C HTSL temperature for Cu wire qual; The 175°C temperature is acceptable as a parallel back-up test to avoid extending qual cycle time.	45	5	3	150	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C and 125C. MSL1/260	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and hot temp 125C.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles Electrical test pre and post stress at hot temp 125C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.